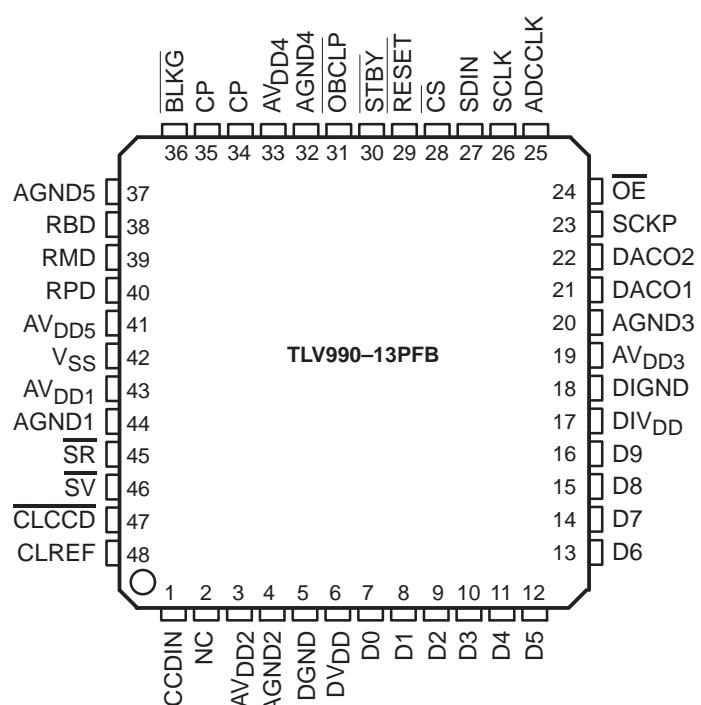


features

- Single-Chip CCD Analog Front-End
- 10-Bit, 13-MSPS, Single 3-V Supply Operation A/D Converter
- Very Low Power: 150-mW Typical, 2-mW Power-Down Mode
- Differential Nonlinearity Error: $< \pm 0.5$ LSB Typical
- Integral Nonlinearity Error: $< \pm 0.9$ LSB Typical
- Programmable Gain Amplifier (PGA) With 0-dB to 36-dB Gain Range (0.045 dB/Step)
- Automatic or Programmable Optical Black Level and Offset Calibration With Digital Filter and Bad Pixel Limits
- Additional DACs for External Analog Setting
- Serial Interface for Register Configuration
- Internal-Reference Voltages
- 48-Pin TQFP Package

application

- Digital Still Camera
- PC Camera

PFB PACKAGE
(TOP VIEW)**description**

The TLV990-13 is a complete CCD signal processor/digitizer designed for digital still camera and PC camera applications. The TLV990-13 performs all the analog-processing functions necessary to maximize the dynamic range, corrects various errors associated with the CCD sensor, and then digitizes the results with an on-chip high-speed analog-to-digital converter (ADC).

The key components of the TLV990-13 include: an input clamp circuit for CCD signal, a correlated double sampler (CDS), a programmable-gain amplifier (PGA) with 0 to 36-dB gain range, two internal digital-to-analog converters (DAC) for automatic or programmable optical black level and offset calibration, a 10-bit, 13-MSPS pipeline ADC, a parallel data port for easy microprocessor interface, a serial port for configuring internal control registers, two additional DACs for external system control, and internal reference voltages.

Designed in advanced CMOS process, the TLV990-13 operates from a single 3-V power supply with a normal power consumption of 150 mW at 13 MSPS and 2 mW in power-down mode.

Its single 3-V operation, very low-power consumption, and fully-integrated analog-processing circuitry make the TLV990-13 an ideal CCD signal-processing solution for digital still cameras and PC camera applications.

This device is available in a 48-pin TQFP package and is specified over a -20°C to 75°C operating-temperature range.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLV990-13PFB	NRND	TQFP	PFB	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-20 to 75	TLV990-13	
TLV990-13PFBG4	NRND	TQFP	PFB	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-20 to 75	TLV990-13	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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16-Apr-2014

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